



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:	)	Group Art Unit: 2827
	)	
Michael John Watson	)	
	)	
Serial Number 09/954,528	)	
	)	Examiner: Chambliss
Filed: September 17, 2001	)	
	)	
Title: IMPROVED ADHESIVES FOR	)	
SEMICONDUCTOR APPLICATIONS	)	
EFFICIENT PROCESSES	)	
FOR PRODUCING SUCH	)	AMENDMENTS TO
DEVICES AND THE DEVICE	)	THE ABSTRACT
PER SE PRODUCED BY THE	)	
EFFICIENT PROCESSES	)	
	)	
Attorney Docket: DC – 4952	)	April 28, 2003

Assistant Commissioner  
For Patents  
Washington DC 20231

Dear Sir:

Please find enclosed a new page setting forth the amended ABSTRACT.

Respectfully submitted,

Robert L. McKellar  
Reg. No. 26,002  
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## ABSTRACT

Die attach adhesives and methods for their use, along with the devices that are obtained by the use of the methods. Using semiconductor chips as an example, the  
5 adhesives and the method for using them provides an interface between a chip (die) and the chip support. The method includes creating a space between the chip and the chip support of a given sized opening by using inorganic insulator particles having an average particle size of 1  $\mu\text{m}$  to 1000  $\mu\text{m}$  and a major axis to minor axis ratio of about 1.0 to 1.5.

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